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IM et al.(10) **Pub. No.: US 2024/0213071 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **ELECTROSTATIC CHUCK****Publication Classification**(71) Applicant: **SAMSUNG ELECTRONICS CO., LTD.**, Suwon-si (KR)(51) **Int. Cl.**  
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An electrostatic chuck includes an electrostatic chuck body having a step portion protruding from a lower end, an adhesive layer disposed on an upper surface of the electrostatic chuck body, a ceramic puck adhered to the adhesive layer and having an edge protruding from the upper surface of the electrostatic chuck body, and a sealant disposed between the step portion and the edge of the ceramic puck and configured to block reaction gas from permeating into the adhesive layer. The sealant includes a coating layer disposed on an external surface thereof, and the coating layer includes a metal oxide including a single rare earth oxide and/or a multilayer heterogeneous metal oxide.

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